CMP User Group Meeting July 2018 @ SEMICON West
Co-Hosted with AIM Photonics

Topic: CMP Technology and Market Trends

Meeting Date: July 11, 2018

Time: 12:30 pm - 5:00 pm

Location: Moscone Center West
Room No. 160
Parking: Nearby Public Parking

REGISTRATION: FREE, JUST SHOW UP!

Co-Chairs:
Ashwani Rawat, Intel Corp., ashwani.k.rawat@intel.com
Todd Buley, Dow Electronic Materials, tbuley@dow.com
Dinesh Koli, Global Foundries, dinesh.koli@globalfoundries.com

SPEAKERS/AGENDA

12:30 - 12:35 PM  Ashwani Rawat/Todd Buley/Dinesh Koli, Opening Remarks/Introductions

12:35 - 1:05 PM  Len Jelinek, IHS Insights, “Global Manufacturing Update – Opportunities and Pitfalls for Manufacturers in 2nd half of 2018 and beyond”

1:05 - 1:35 PM  Sai Vegunta, Micron, “Next Gen CMP Challenges for 3D Memory Architectures”

1:35 - 2:00 PM  Olga Samsonenka, Andy Kim, University of Washington, “Investigation of NMR-based Surface Area Measurement as a Quality Monitor for Nanoparticle Silica Abrasives”

2:00 - 2:25 PM  Gabriela Diaz a, Lauren Peckler a, Yasa Sampurno a,b, Ara Philipossian a,b, a University of Arizona, b Araca Incorporated, Tucson, AZ, “New Insights into the Tribological and Kinetic Attributes of Retaining Rings in Chemical Mechanical Planarization”

2:25 - 2:40 PM  Coffee/Networking Break


3:35 – 4:00PM  Alex Tregub, Intel, “Developing Robust Quality Systems for CMP Solid Consumables”

4:00PM-4:25PM  Mike Corbett, Linx Consulting, “Impact of Advanced Memory Technologies on CMP Industry”


4:50PM – 5:00PM  Ashwani Rawat/Todd Buley/Dinesh Koli, Concluding Remarks/Wrap-up

All presentations will be posted on the CMPUG Proceedings webpage approximately 1-2 weeks following the meeting.

If you would like to sponsor a future User Group meeting please check out the new NCCAVS Sponsorship opportunities.